

	Type	L #	Hits	Search Text
1	BRS	L1	2772	planarization.clm.
2	BRS	L2	1433	1 and (mechanical\$5).clm.
3	BRS	L3	80	2 and (stress strain load).clm.
4	BRS	L4	40	3 and (computer processor microprocessor CPU ECU)
5	BRS	L5	0	4 and (eddy)
6	BRS	L6	31	1 and (eddy)
7	BRS	L7	22	6 and (stress strain load)
8	BRS	L8	16	7 and (computer processor. microprocessor CPU ECU)
9	BRS	L9	3342	planarization.ti.
10	BRS	L10	6	9 and (eddy)
11	BRS	L11	6	10 and (stress strain load pressure)
12	BRS	L12	1	11 and (relie\$4)
13	BRS	L13	2772	planarization.clm.
14	BRS	L14	31	13 and (eddy)
15	BRS	L15	23	14 and (computer processor microprocessor CPU ECU)
16	BRS	L16	20	15 and (wafer)
17	BRS	L17	18	16 and (sensor detector transducer)
18	BRS	L18	16	17 and (temperature)
19	BRS	L19	16	18 and (temperature)
20	BRS	L22	0	21 and (map\$4)

	DBs	Time Stamp	Comments	Error Definition	Errors
1	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:39			0
2	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:39			0
3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:42			0
4	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:42			0
5	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:42			0
6	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:45			0
7	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:44			0
8	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:45			0
9	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:45			0
10	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:43			0
11	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:50			0
12	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:44			0
13	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:45			0
14	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:49			0
15	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:50			0
16	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:50			0
17	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:46			0
18	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:46			0
19	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:47			0
20	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:50			0

	Type	L #	Hits	Search Text
21	BRS	L23	15	1 and (map\$4).clm.
22	BRS	L24	3	23 and (eddy)
23	BRS	L25	4756	"chemical mechanical planarization"
24	BRS	L26	161	25 and (map\$4)
25	BRS	L27	150	26 and (wafer)
26	BRS	L28	106	27 and (stress strain load pressure)
27	BRS	L29	88	28 and (computer processor microprocessor CPU ECU)
28	BRS	L30	7	29 and (eddy)
29	BRS	L31	762	"chemical mechanical planarization".clm.
30	BRS	L32	9	31 and (map\$4).clm.
31	BRS	L34	3	33 and (eddy)
32	BRS	L33	9	32 and (computer processor microprocessor CPU ECU)
33	BRS	L21	10	20 and (motor)
34	BRS	L20	12	19 and (thermal\$4)

	DBs	Time Stamp	Comments	Error Definition	Errors
21	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:49			0
22	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:50			0
23	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:51			0
24	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:51			0
25	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:50			0
26	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:50			0
27	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:52			0
28	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:52			0
29	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:51			0
30	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:51			0
31	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:52			0
32	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:52			0
33	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:54			0
34	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/22 11:55			0